



128K x 32, 128K x 36, 256K x 18 4 Mb SYNCHRONOUS FLOW-THROUGH STATIC RAM

SEPTEMBER 2011

FEATURES

- Internal self-timed write cycle
- Individual Byte Write Control and Global Write
- Clock controlled, registered address, data and control
- Burst sequence control using MODE input
- Three chip enable option for simple depth expansion and address pipelining
- Common data inputs and data outputs
- Auto Power-down during deselect
- Single cycle deselect
- Snooze MODE for reduced-power standby
- Power Supply
 LF: $V_{DD} 3.3V \pm 5\%$, $V_{DDQ} 3.3V/2.5V \pm 5\%$
 VF: $V_{DD} 2.5V -5\% +10\%$, $V_{DDQ} 2.5V -5\% +10\%$
- JEDEC 100-Pin TQFP, 119-pin PBGA, and 165-pin PBGA packages
- Automotive temperature available
- Lead-free available

DESCRIPTION

The *ISSI* IS61(64)LF12832A, IS64VF12832A, IS61(64)LF/VF12836A and IS61(64)LF/VF25618A are high-speed, low-power synchronous static RAMs designed to provide burstable, high-performance memory for communication and networking applications. The IS61(64)LF12832A is organized as 131,072 words by 32 bits. The IS61(64)LF/VF12836A is organized as 131,072 words by 36 bits. The IS61(64)LF/VF25618A is organized as 262,144 words by 18 bits. Fabricated with *ISSI*'s advanced CMOS technology, the device integrates a 2-bit burst counter, high-speed SRAM core, and high-drive capability outputs into a single monolithic circuit. All synchronous inputs pass through registers controlled by a positive-edge-triggered single clock input.

Write cycles are internally self-timed and are initiated by the rising edge of the clock input. Write cycles can be one to four bytes wide as controlled by the write control inputs.

Separate byte enables allow individual bytes to be written. Byte write operation is performed by using byte write enable (\overline{BWE}) input combined with one or more individual byte write signals (\overline{BWx}). In addition, Global Write (\overline{GW}) is available for writing all bytes at one time, regardless of the byte write controls.

Bursts can be initiated with either \overline{ADSP} (Address Status Processor) or \overline{ADSC} (Address Status Cache Controller) input pins. Subsequent burst addresses can be generated internally and controlled by the \overline{ADV} (burst address advance) input pin.

The mode pin is used to select the burst sequence order, Linear burst is achieved when this pin is tied LOW. Interleave burst is achieved when this pin is tied HIGH or left floating.

FAST ACCESS TIME

| Symbol | Parameter | -6.5 | -7.5 | Units |
|--------|-------------------|------|------|-------|
| tkQ | Clock Access Time | 6.5 | 7.5 | ns |
| tkc | Cycle Time | 7.5 | 8.5 | ns |
| | Frequency | 133 | 117 | MHz |

Copyright © 2011 Integrated Silicon Solution, Inc. All rights reserved. ISSI reserves the right to make changes to this specification and its products at any time without notice. ISSI assumes no liability arising out of the application or use of any information, products or services described herein. Customers are advised to obtain the latest version of this device specification before relying on any published information and before placing orders for products.

Integrated Silicon Solution, Inc. does not recommend the use of any of its products in life support applications where the failure or malfunction of the product can reasonably be expected to cause failure of the life support system or to significantly affect its safety or effectiveness. Products are not authorized for use in such applications unless Integrated Silicon Solution, Inc. receives written assurance to its satisfaction, that:

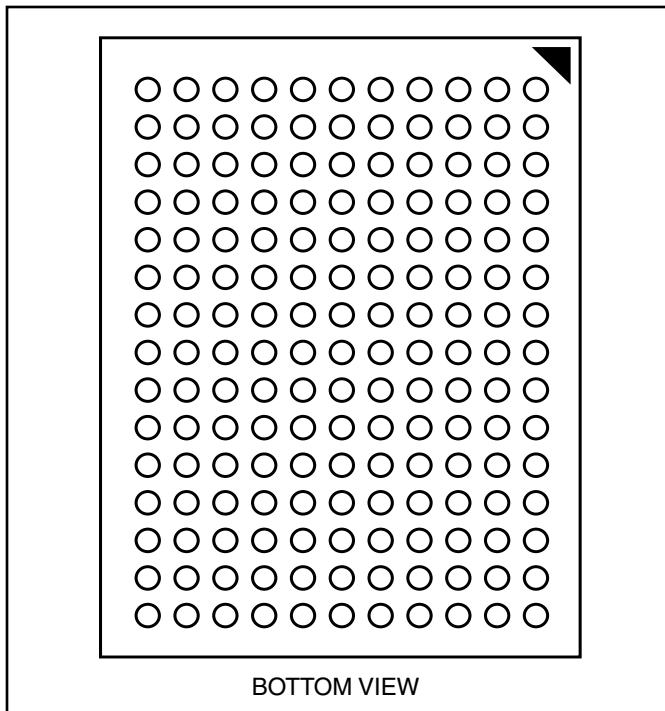
- a.) the risk of injury or damage has been minimized;
- b.) the user assume all such risks; and
- c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

BLOCK DIAGRAM



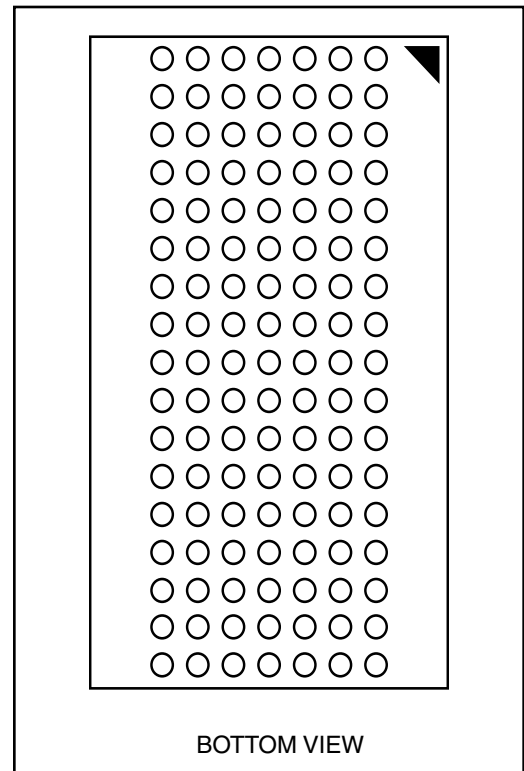
165-PIN BGA

165-Ball, 13x15 mm BGA



119-PIN BGA

119-Ball, 14x22 mm BGA



119 BGA PACKAGE PIN CONFIGURATION

128K x 36 (TOP VIEW)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
|----------|------------------|-----------------|-------------------------|--------------------------|-------------------------|-------------------------|------------------|
| A | V _{DDQ} | A | A | $\overline{\text{ADSP}}$ | A | A | V _{DDQ} |
| B | NC | CE2 | A | $\overline{\text{ADSC}}$ | A | $\overline{\text{CE2}}$ | NC |
| C | NC | A | A | V _{DD} | A | A | NC |
| D | DQc | DQPc | V _{SS} | NC | V _{SS} | DQPb | DQb |
| E | DQc | DQc | V _{SS} | $\overline{\text{CE}}$ | V _{SS} | DQb | DQb |
| F | V _{DDQ} | DQc | V _{SS} | $\overline{\text{OE}}$ | V _{SS} | DQb | V _{DDQ} |
| G | DQc | DQc | $\overline{\text{BWc}}$ | $\overline{\text{ADV}}$ | $\overline{\text{BWb}}$ | DQb | DQb |
| H | DQc | DQc | V _{SS} | $\overline{\text{GW}}$ | V _{SS} | DQb | DQb |
| J | V _{DDQ} | V _{DD} | NC | V _{DD} | NC | V _{DD} | V _{DDQ} |
| K | DQd | DQd | V _{SS} | CLK | V _{SS} | DQa | DQa |
| L | DQd | DQd | $\overline{\text{BWd}}$ | NC | $\overline{\text{BWA}}$ | DQa | DQa |
| M | V _{DDQ} | DQd | V _{SS} | $\overline{\text{BWE}}$ | V _{SS} | DQa | V _{DDQ} |
| N | DQd | DQd | V _{SS} | A ₁ * | V _{SS} | DQa | DQa |
| P | DQd | DQPd | V _{SS} | A ₀ * | V _{SS} | DQPa | DQa |
| R | NC | A | MODE | V _{DD} | NC | A | NC |
| T | NC | NC | A | A | A | NC | ZZ |
| U | V _{DDQ} | NC | NC | NC | NC | NC | V _{DDQ} |

Note: * A₀ and A₁ are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

| Symbol | Pin Name |
|---|-----------------------------------|
| A | Address Inputs |
| A ₀ , A ₁ | Synchronous Burst Address Inputs |
| $\overline{\text{ADV}}$ | Synchronous Burst Address Advance |
| $\overline{\text{ADSP}}$ | Address Status Processor |
| $\overline{\text{ADSC}}$ | Address Status Controller |
| $\overline{\text{GW}}$ | Global Write Enable |
| CLK | Synchronous Clock |
| $\overline{\text{CE}}$, CE2, $\overline{\text{CE2}}$ | Synchronous Chip Select |
| $\overline{\text{BWx}}$ (x=a-d) | Synchronous Byte Write Controls |
| $\overline{\text{BWE}}$ | Byte Write Enable |

| Symbol | Pin Name |
|------------------------|--------------------------|
| $\overline{\text{OE}}$ | Output Enable |
| ZZ | Power Sleep Mode |
| MODE | Burst Sequence Selection |
| NC | No Connect |
| DQa-DQd | Data Inputs/Outputs |
| DQPa-Pd | Output Power Supply |
| V _{DD} | Power Supply |
| V _{DDQ} | Output Power Supply |
| V _{SS} | Ground |

119 BGA PACKAGE PIN CONFIGURATION

256Kx18 (TOP VIEW)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 |
|----------|------------------|------------------|-------------------------|--------------------------|-------------------------|-------------------------|------------------|
| A | V _{DDQ} | A | A | $\overline{\text{ADSP}}$ | A | A | V _{DDQ} |
| B | NC | CE2 | A | $\overline{\text{ADSC}}$ | A | $\overline{\text{CE2}}$ | NC |
| C | NC | A | A | V _{DD} | A | A | NC |
| D | DQb | NC | V _{SS} | NC | V _{SS} | DQP _a | NC |
| E | NC | DQb | V _{SS} | $\overline{\text{CE}}$ | V _{SS} | NC | DQ _a |
| F | V _{DDQ} | NC | V _{SS} | $\overline{\text{OE}}$ | V _{SS} | DQ _a | V _{DDQ} |
| G | NC | DQb | $\overline{\text{BWb}}$ | $\overline{\text{ADV}}$ | V _{SS} | NC | DQ _a |
| H | DQb | NC | V _{SS} | $\overline{\text{GW}}$ | V _{SS} | DQ _a | NC |
| J | V _{DDQ} | V _{DD} | NC | V _{DD} | NC | V _{DD} | V _{DDQ} |
| K | NC | DQb | V _{SS} | CLK | V _{SS} | NC | DQ _a |
| L | DQb | NC | V _{SS} | NC | $\overline{\text{BWa}}$ | DQ _a | NC |
| M | V _{DDQ} | DQb | V _{SS} | $\overline{\text{BWE}}$ | V _{SS} | NC | V _{DDQ} |
| N | DQb | NC | V _{SS} | A ₁ * | V _{SS} | DQ _a | NC |
| P | NC | DQP _b | V _{SS} | A ₀ * | V _{SS} | NC | DQ _a |
| R | NC | A | MODE | V _{DD} | NC | A | NC |
| T | NC | A | A | NC | A | A | ZZ |
| U | V _{DDQ} | NC | NC | NC | NC | NC | V _{DDQ} |

Note: * A₀ and A₁ are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

| Symbol | Pin Name |
|---|-----------------------------------|
| A | Address Inputs |
| A ₀ , A ₁ | Synchronous Burst Address Inputs |
| $\overline{\text{ADV}}$ | Synchronous Burst Address Advance |
| $\overline{\text{ADSP}}$ | Address Status Processor |
| $\overline{\text{ADSC}}$ | Address Status Controller |
| $\overline{\text{GW}}$ | Global Write Enable |
| CLK | Synchronous Clock |
| $\overline{\text{CE}}$, CE2, $\overline{\text{CE2}}$ | Synchronous Chip Select |
| $\overline{\text{BWx}}$ (x=a,b) | Synchronous Byte Write Controls |
| $\overline{\text{BWE}}$ | Byte Write Enable |

| Symbol | Pin Name |
|----------------------------------|--------------------------|
| $\overline{\text{OE}}$ | Output Enable |
| ZZ | Power Sleep Mode |
| MODE | Burst Sequence Selection |
| NC | No Connect |
| DQ _a -DQ _b | Data Inputs/Outputs |
| DQP _a -P _b | Output Power Supply |
| V _{DD} | Power Supply |
| V _{DDQ} | Output Power Supply |
| V _{SS} | Ground |



165 PBGA PACKAGE PIN CONFIGURATION

128K x 36 (TOP VIEW)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 |
|----------|------|-----|-----------------|------------------|------------------|-----|------------------|-----------------|-------------------|-----|------|
| A | NC | A | \overline{CE} | BWc | BWb | CE2 | \overline{BWE} | ADSC | \overline{ADV} | A | NC |
| B | NC | A | CE2 | \overline{BWd} | \overline{BWa} | CLK | \overline{GW} | \overline{OE} | \overline{ADSP} | A | NC |
| C | DQPc | NC | VDDQ | VSS | VSS | VSS | VSS | VSS | VDDQ | NC | DQPb |
| D | DQc | DQc | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQb | DQb |
| E | DQc | DQc | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQb | DQb |
| F | DQc | DQc | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQb | DQb |
| G | DQc | DQc | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQb | DQb |
| H | NC | NC | NC | VDD | VSS | VSS | VSS | VDD | NC | NC | ZZ |
| J | DQd | DQd | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQa | DQa |
| K | DQd | DQd | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQa | DQa |
| L | DQd | DQd | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQa | DQa |
| M | DQd | DQd | VDDQ | VDD | VSS | VSS | VSS | VDD | VDDQ | DQa | DQa |
| N | DQPd | NC | VDDQ | VSS | NC | NC | NC | VSS | VDDQ | NC | DQPa |
| P | NC | NC | A | A | NC | A1* | NC | A | A | A | NC |
| R | MODE | NC | A | A | NC | A0* | NC | A | A | A | A |

Note: * A0 and A1 are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

| Symbol | Pin Name |
|------------------------------|-----------------------------------|
| A | Address Inputs |
| A0, A1 | Synchronous Burst Address Inputs |
| \overline{ADV} | Synchronous Burst Address Advance |
| \overline{ADSP} | Address Status Processor |
| \overline{ADSC} | Address Status Controller |
| \overline{GW} | Global Write Enable |
| CLK | Synchronous Clock |
| \overline{CE} , CE2, CE2 | Synchronous Chip Select |
| \overline{BWx} (x=a,b,c,d) | Synchronous Byte Write Controls |

| Symbol | Pin Name |
|------------------|---|
| \overline{BWE} | Byte Write Enable |
| \overline{OE} | Output Enable |
| ZZ | Power Sleep Mode |
| MODE | Burst Sequence Selection |
| NC | No Connect |
| DQx | Data Inputs/Outputs |
| DQPx | Data Inputs/Outputs |
| VDD | 3.3V/2.5V Power Supply |
| VDDQ | Isolated Output Power Supply 3.3V/2.5V |
| VSS | Ground |



165 PBGA PACKAGE PIN CONFIGURATION

256K x 18 (TOP VIEW)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 |
|----------|------------------|-----------------|------------------|------------------|------------------|------------------|------------------|-------------------|-------------------|-----------------|------------------|
| A | NC | A | \overline{CE} | \overline{BWb} | NC | $\overline{CE2}$ | \overline{BWE} | \overline{ADSC} | ADV | A | A |
| B | NC | A | CE2 | NC | \overline{BWa} | CLK | \overline{GW} | \overline{OE} | \overline{ADSP} | A | NC |
| C | NC | NC | V _{DDQ} | V _{SS} | V _{SS} | V _{SS} | V _{SS} | V _{SS} | V _{DDQ} | NC | DQP _a |
| D | NC | DQ _b | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | NC | DQ _a |
| E | NC | DQ _b | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | NC | DQ _a |
| F | NC | DQ _b | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | NC | DQ _a |
| G | NC | DQ _b | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | NC | DQ _a |
| H | NC | NC | NC | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | NC | NC | ZZ |
| J | DQ _b | NC | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | DQ _a | NC |
| K | DQ _b | NC | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | DQ _a | NC |
| L | DQ _b | NC | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | DQ _a | NC |
| M | DQ _b | NC | V _{DDQ} | V _{DD} | V _{SS} | V _{SS} | V _{SS} | V _{DD} | V _{DDQ} | DQ _a | NC |
| N | DQP _b | NC | V _{DDQ} | V _{SS} | NC | NC | NC | V _{SS} | V _{DDQ} | NC | NC |
| P | NC | NC | A | A | NC | A ₁ * | NC | A | A | A | NC |
| R | MODE | NC | A | A | NC | A ₀ * | NC | A | A | A | A |

Note: * A₀ and A₁ are the two least significant bits (LSB) of the address field and set the internal burst counter if burst is desired.

PIN DESCRIPTIONS

| Symbol | Pin Name |
|--|-----------------------------------|
| A | Address Inputs |
| A ₀ , A ₁ | Synchronous Burst Address Inputs |
| ADV | Synchronous Burst Address Advance |
| \overline{ADSP} | Address Status Processor |
| \overline{ADSC} | Address Status Controller |
| \overline{GW} | Global Write Enable |
| CLK | Synchronous Clock |
| \overline{CE} , $\overline{CE2}$, CE2 | Synchronous Chip Select |
| \overline{BWx} (x=a,b) | Synchronous Byte Write Controls |

| Symbol | Pin Name |
|------------------|---|
| \overline{BWE} | Byte Write Enable |
| \overline{OE} | Output Enable |
| ZZ | Power Sleep Mode |
| MODE | Burst Sequence Selection |
| NC | No Connect |
| DQ _x | Data Inputs/Outputs |
| DQP _x | Data Inputs/Outputs |
| V _{DD} | 3.3V/2.5V Power Supply |
| V _{DDQ} | Isolated Output Power Supply 3.3V/2.5V |
| V _{SS} | Ground |

PIN CONFIGURATION

100-PIN TQFP (128K x 36)

100-PIN TQFP (128K x 32)



PIN DESCRIPTIONS

| | |
|--------------|--|
| A0, A1 | Synchronous Address Inputs. These pins must tied to the two LSBs of the address bus. |
| A | Synchronous Address Inputs |
| ADSC | Synchronous Controller Address Status |
| ADSP | Synchronous Processor Address Status |
| ADV | Synchronous Burst Address Advance |
| BWa-BWd | Synchronous Byte Write Enable |
| BWE | Synchronous Byte Write Enable |
| CE, CE2, CE2 | Synchronous Chip Enable |
| CLK | Synchronous Clock |

| | |
|-----------|---|
| DQa-DQd | Synchronous Data Input/Output |
| DQPa-DQPd | Parity Data Input/Output |
| GW | Synchronous Global Write Enable |
| MODE | Burst Sequence Mode Selection |
| OE | Output Enable |
| VDD | 3.3V/2.5V Power Supply |
| VDDQ | Isolated Output Buffer Supply: 3.3V/2.5V |
| Vss | Ground |
| ZZ | Snooze Enable |

PIN CONFIGURATION

100-PIN TQFP (256K x 18)



PIN DESCRIPTIONS

| | |
|----------------------------|--|
| A0, A1 | Synchronous Address Inputs. These pins must tied to the two LSBs of the address bus. |
| A | Synchronous Address Inputs |
| ADSC | Synchronous Controller Address Status |
| ADSP | Synchronous Processor Address Status |
| ADV | Synchronous Burst Address Advance |
| BW \bar{a} -BW \bar{b} | Synchronous Byte Write Enable |
| BWE | Synchronous Byte Write Enable |
| CE, CE2, CE2 | Synchronous Chip Enable |
| CLK | Synchronous Clock |
| DQa-DQb | Synchronous Data Input/Output |

| | |
|------------------------------|---|
| DQP \bar{a} -DQP \bar{b} | Parity Data I/O; DQP \bar{a} is parity for DQ \bar{a} 1-8; DQP \bar{b} is parity for DQ \bar{b} 1-8 |
| GW | Synchronous Global Write Enable |
| MODE | Burst Sequence Mode Selection |
| OE | Output Enable |
| VDD | 3.3V/2.5V Power Supply |
| VDDQ | Isolated Output Buffer Supply: 3.3V/2.5V |
| Vss | Ground |
| ZZ | Snooze Enable |



TRUTH TABLE⁽¹⁻⁸⁾

| OPERATION | ADDRESS | \overline{CE} | $\overline{CE2}$ | CE2 | ZZ | \overline{ADSP} | \overline{ADSC} | \overline{ADV} | \overline{WRITE} | \overline{OE} | CLK | DQ |
|-----------------------------|----------|-----------------|------------------|-----|----|-------------------|-------------------|------------------|--------------------|-----------------|-----|--------|
| Deselect Cycle, Power-Down | None | H | X | X | L | X | L | X | X | X | L-H | High-Z |
| Deselect Cycle, Power-Down | None | L | X | L | L | L | X | X | X | X | L-H | High-Z |
| Deselect Cycle, Power-Down | None | L | H | X | L | L | X | X | X | X | L-H | High-Z |
| Deselect Cycle, Power-Down | None | L | X | L | L | H | L | X | X | X | L-H | High-Z |
| Deselect Cycle, Power-Down | None | L | H | X | L | H | L | X | X | X | L-H | High-Z |
| Snooze Mode, Power-Down | None | X | X | X | H | X | X | X | X | X | X | High-Z |
| Read Cycle, Begin Burst | External | L | L | H | L | L | X | X | X | L | L-H | Q |
| Read Cycle, Begin Burst | External | L | L | H | L | L | X | X | X | H | L-H | High-Z |
| Write Cycle, Begin Burst | External | L | L | H | L | H | L | X | L | X | L-H | D |
| Read Cycle, Begin Burst | External | L | L | H | L | H | L | X | H | L | L-H | Q |
| Read Cycle, Begin Burst | External | L | L | H | L | H | L | X | H | H | L-H | High-Z |
| Read Cycle, Continue Burst | Next | X | X | X | L | H | H | L | H | L | L-H | Q |
| Read Cycle, Continue Burst | Next | X | X | X | L | H | H | L | H | H | L-H | High-Z |
| Read Cycle, Continue Burst | Next | H | X | X | L | X | H | L | H | L | L-H | Q |
| Read Cycle, Continue Burst | Next | H | X | X | L | X | H | L | H | H | L-H | High-Z |
| Write Cycle, Continue Burst | Next | X | X | X | L | H | H | L | L | X | L-H | D |
| Write Cycle, Continue Burst | Next | H | X | X | L | X | H | L | L | X | L-H | D |
| Read Cycle, Suspend Burst | Current | X | X | X | L | H | H | H | H | L | L-H | Q |
| Read Cycle, Suspend Burst | Current | X | X | X | L | H | H | H | H | H | L-H | High-Z |
| Read Cycle, Suspend Burst | Current | H | X | X | L | X | H | H | H | L | L-H | Q |
| Read Cycle, Suspend Burst | Current | H | X | X | L | X | H | H | H | H | L-H | High-Z |
| Write Cycle, Suspend Burst | Current | X | X | X | L | H | H | H | L | X | L-H | D |
| Write Cycle, Suspend Burst | Current | H | X | X | L | X | H | H | L | X | L-H | D |

NOTE:

1. X means "Don't Care." H means logic HIGH. L means logic LOW.
2. For \overline{WRITE} , L means one or more byte write enable signals ($\overline{BWA-d}$) and \overline{BWE} are LOW or \overline{GW} is LOW. $\overline{WRITE} = H$ for all \overline{BWx} , \overline{BWE} , \overline{GW} HIGH.
3. \overline{BWA} enables WRITES to DQa's and DQP_a. \overline{BWb} enables WRITES to DQb's and DQP_b. \overline{BWC} enables WRITES to DQc's and DQP_c. \overline{BWD} enables WRITES to DQd's and DQP_d. DQP_a and DQP_b are available on the x18 version. DQP_a-DQP_d are available on the x36 version.
4. All inputs except \overline{OE} and ZZ must meet setup and hold times around the rising edge (LOW to HIGH) of CLK.
5. Wait states are inserted by suspending burst.
6. For a WRITE operation following a READ operation, \overline{OE} must be HIGH before the input data setup time and held HIGH during the input data hold time.
7. This device contains circuitry that will ensure the outputs will be in High-Z during power-up.
8. \overline{ADSP} LOW always initiates an internal READ at the L-H edge of CLK. A WRITE is performed by setting one or more byte write enable signals and \overline{BWE} LOW or \overline{GW} LOW for the subsequent L-H edge of CLK. See WRITE timing diagram for clarification.

PARTIAL TRUTH TABLE

| Function | \overline{GW} | \overline{BWE} | \overline{BWA} | \overline{BWb} | \overline{BWC} | \overline{BWD} |
|-----------------|-----------------|------------------|------------------|------------------|------------------|------------------|
| Read | H | H | X | X | X | X |
| Read | H | L | H | H | H | H |
| Write Byte 1 | H | L | L | H | H | H |
| Write All Bytes | H | L | L | L | L | L |
| Write All Bytes | L | X | X | X | X | X |

INTERLEAVED BURST ADDRESS TABLE (MODE = V_{DD} or No Connect)

| External Address A1 A0 | 1st Burst Address A1 A0 | 2nd Burst Address A1 A0 | 3rd Burst Address A1 A0 |
|---------------------------|----------------------------|----------------------------|----------------------------|
| 00 | 01 | 10 | 11 |
| 01 | 00 | 11 | 10 |
| 10 | 11 | 00 | 01 |
| 11 | 10 | 01 | 00 |

LINEAR BURST ADDRESS TABLE (MODE = V_{SS})



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

| Symbol | Parameter | Value | Unit |
|------------------------------------|---|--------------------------------|------|
| T _{STG} | Storage Temperature | -55 to +150 | °C |
| P _D | Power Dissipation | 1.6 | W |
| I _{OUT} | Output Current (per I/O) | 100 | mA |
| V _{IN} , V _{OUT} | Voltage Relative to V _{SS} for I/O Pins | -0.5 to V _{DDQ} + 0.5 | V |
| V _{IN} | Voltage Relative to V _{SS} for for Address and Control Inputs | -0.5 to V _{DD} + 0.5 | V |
| V _{DD} | Voltage on V _{DD} Supply Relative to V _{SS} | -0.5 to 4.6 | V |

Notes:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, precautions may be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.
3. This device contains circuitry that will ensure the output devices are in High-Z at power up.

OPERATING RANGE (IS61/64LFxxxxx)

| Range | Ambient Temperature | V _{DD} | V _{DDQ} |
|------------|---------------------|-----------------|------------------|
| Commercial | 0°C to +70°C | 3.3V ± 5% | 3.3V/2.5V ± 5% |
| Industrial | -40°C to +85°C | 3.3V ± 5% | 3.3V/2.5V ± 5% |
| Automotive | -40°C to +125°C | 3.3V ± 5% | 3.3V/2.5V ± 5% |

OPERATING RANGE (IS61/64VFxxxxx)

| Range | Ambient Temperature | V _{DD} | V _{DDQ} |
|------------|---------------------|-----------------|------------------|
| Commercial | 0°C to +70°C | 2.5V -5% +10% | 2.5V -5% +10% |
| Industrial | -40°C to +85°C | 2.5V -5% +10% | 2.5V -5% +10% |
| Automotive | -40°C to +125°C | 2.5V -5% +10% | 2.5V -5% +10% |

DC ELECTRICAL CHARACTERISTICS (Over Operating Range)

| Symbol | Parameter | Test Conditions | 3.3V | | 2.5V | | Unit |
|-----------------|-----------------------------------|--|------|-----------------------|------|-----------------------|------|
| | | | Min. | Max. | Min. | Max. | |
| V _{OH} | Output HIGH Voltage | I _{OH} = -4.0 mA (3.3V) I _{OH} = -1.0 mA (2.5V) | 2.4 | — | 2.0 | — | V |
| V _{OL} | Output LOW Voltage | I _{OL} = 8.0 mA (3.3V) I _{OL} = 1.0 mA (2.5V) | — | 0.4 | — | 0.4 | V |
| V _{IH} | Input HIGH Voltage ⁽¹⁾ | | 2.0 | V _{DD} + 0.3 | 1.7 | V _{DD} + 0.3 | V |
| V _{IL} | Input LOW Voltage ⁽¹⁾ | | -0.3 | 0.8 | -0.3 | 0.7 | V |
| I _{LI} | Input Leakage Current | V _{SS} ≤ V _{IN} ≤ V _{DD} ⁽¹⁾ | -5 | 5 | -5 | 5 | μA |
| I _{LO} | Output Leakage Current | V _{SS} ≤ V _{OUT} ≤ V _{DDQ} , $\overline{OE} = V_{IH}$ | -5 | 5 | -5 | 5 | μA |

Note:

- V_{ILL}(min) = -2.0V AC (pulse width < t_{KC}/ 2). Guaranteed by design.
 V_{IHH}(max) = V_{DD} + 1.5V AC (pulse width < t_{KC}/ 2). Guaranteed by design.



POWER SUPPLY CHARACTERISTICS⁽¹⁾ (Over Operating Range)

| Symbol | Parameter | Test Conditions | Temp. range | 6.5 MAX | | 7.5 MAX | | Unit |
|------------------|--------------------------------|---|---------------------|------------|---------|------------|---------|------|
| | | | | x18 | x32/x36 | x18 | x32/x36 | |
| I _{CC} | AC Operating Supply Current | Device Selected, | Com. | 175 | 175 | 155 | 155 | mA |
| | | $\overline{OE} = V_{IH}$, $ZZ \leq V_{IL}$, | Ind. | 180 | 180 | 160 | 160 | |
| | | All Inputs $\leq 0.2V$ or $\geq V_{DD} - 0.2V$, | Auto. | 190 | 190 | 175 | 175 | |
| | | Cycle Time $\geq t_{kc}$ min. | typ. ⁽²⁾ | 120 | | 110 | | |
| I _{SB} | Standby Current TTL Input | Device Deselected, | Com. | 90 | 90 | 90 | 90 | mA |
| | | $V_{DD} = \text{Max.}$, | Ind. | 100 | 100 | 100 | 100 | |
| | | All Inputs $\leq V_{IL}$ or $\geq V_{IH}$, $ZZ \leq V_{IL}$, $f = \text{Max.}$ | Auto. | 120 | 120 | 120 | 120 | |
| I _{SBI} | Standby Current CMOS Input | Device Deselected, | Com. | 70 | 70 | 70 | 70 | mA |
| | | $V_{DD} = \text{Max.}$, | Ind. | 75 | 75 | 75 | 75 | |
| | | $V_{IN} \leq V_{SS} + 0.2V$ or $\geq V_{DD} - 0.2V$ | Auto. | 90 | 90 | 90 | 90 | |
| | | $f = 0$ | typ. | 40 | | 40 | | |
| I _{SB2} | Sleep Mode | $ZZ > V_{IH}$ | Com. | 30 | 30 | 30 | 30 | mA |
| | | | Ind. | 35 | 35 | 35 | 35 | |
| | | | Auto. | 45 | 45 | 45 | 45 | |
| | | | typ. | 25 | | 25 | | |

Note:

- MODE pin has an internal pullup and should be tied to V_{DD} or V_{SS} . It exhibits $\pm 100 \mu A$ maximum leakage current when tied to $\leq V_{SS} + 0.2V$ or $\geq V_{DD} - 0.2V$.
- Typical values are measured at $V_{DD} = 3.3V$, $T_A = 25^\circ C$ and not 100% tested.

CAPACITANCE^(1,2)

| Symbol | Parameter | Conditions | Max. | Unit |
|------------------|--------------------------|----------------|------|------|
| C _{IN} | Input Capacitance | $V_{IN} = 0V$ | 6 | pF |
| C _{OUT} | Input/Output Capacitance | $V_{OUT} = 0V$ | 8 | pF |

Notes:

- Tested initially and after any design or process changes that may affect these parameters.
- Test conditions: $T_A = 25^\circ C$, $f = 1 \text{ MHz}$, $V_{DD} = 3.3V$.

3.3V I/O AC TEST CONDITIONS

| Parameter | Unit |
|---|---------------------|
| Input Pulse Level | 0V to 3.0V |
| Input Rise and Fall Times | 1.5 ns |
| Input and Output Timing and Reference Level | 1.5V |
| Output Load | See Figures 1 and 2 |

AC TEST LOADS



Figure 1

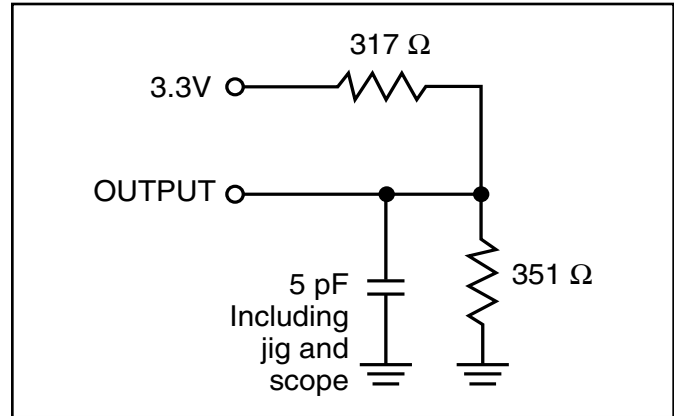


Figure 2

2.5V I/O AC TEST CONDITIONS

| Parameter | Unit |
|---|---------------------|
| Input Pulse Level | 0V to 2.5V |
| Input Rise and Fall Times | 1.5 ns |
| Input and Output Timing and Reference Level | 1.25V |
| Output Load | See Figures 3 and 4 |

2.5V I/O OUTPUT LOAD EQUIVALENT



Figure 3



Figure 4



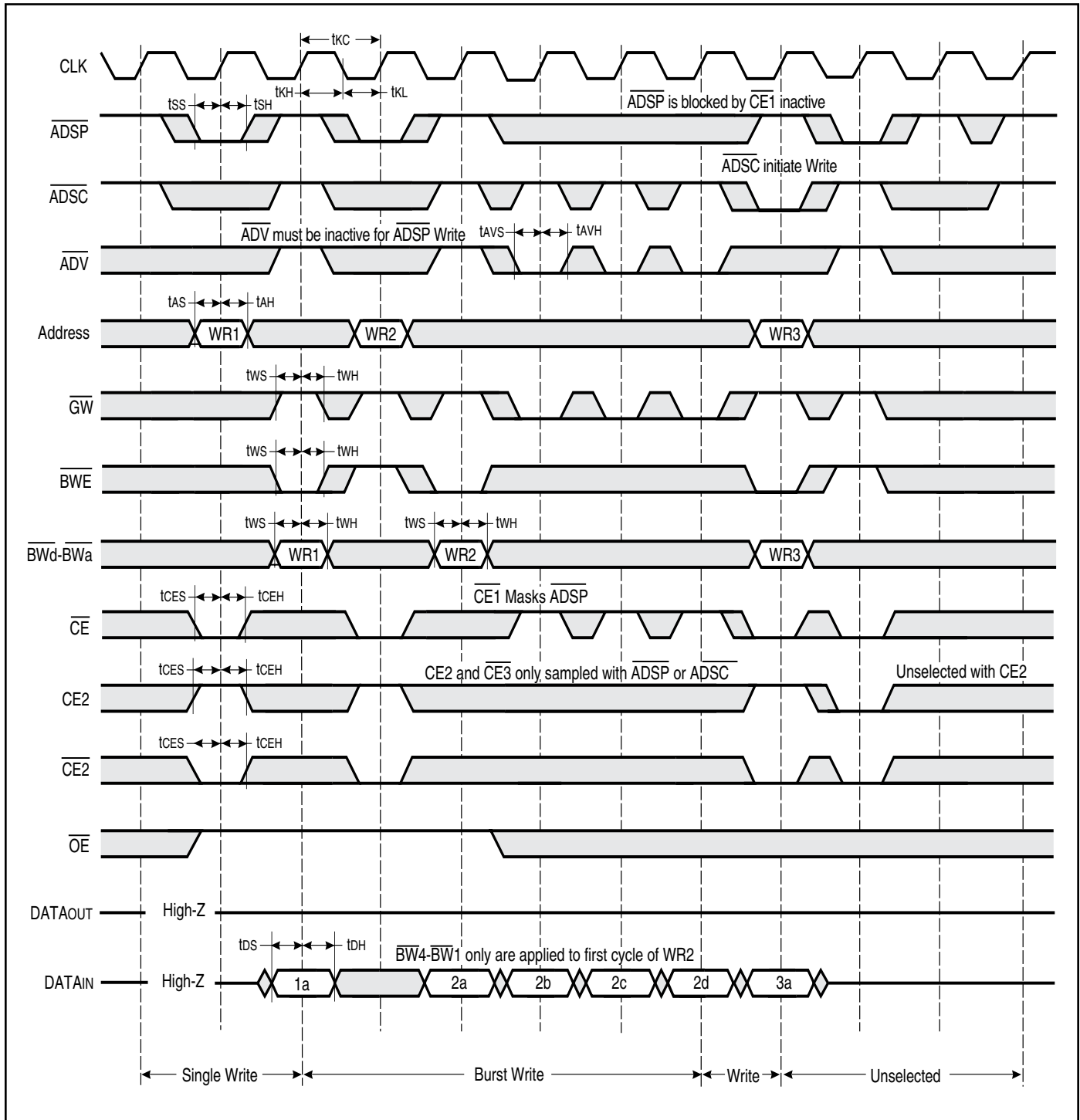
READ/WRITE CYCLE SWITCHING CHARACTERISTICS⁽¹⁾ (Over Operating Range)

| Symbol | Parameter | 6.5 | | 7.5 | | Unit |
|------------------------------------|---------------------------------|------|------|------|------|------|
| | | Min. | Max. | Min. | Max. | |
| fmax | Clock Frequency | — | 133 | — | 117 | MHz |
| t _{KC} | Cycle Time | 7.5 | — | 8.5 | — | ns |
| t _{KH} | Clock High Time | 2.2 | — | 2.5 | — | ns |
| t _{KL} | Clock Low Time | 2.2 | — | 2.5 | — | ns |
| t _{KQ} | Clock Access Time | — | 6.5 | — | 7.5 | ns |
| t _{KQX} ⁽²⁾ | Clock High to Output Invalid | 2.5 | — | 2.5 | — | ns |
| t _{KQLZ} ^(2,3) | Clock High to Output Low-Z | 2.5 | — | 2.5 | — | ns |
| t _{KQHZ} ^(2,3) | Clock High to Output High-Z | — | 3.8 | — | 4.0 | ns |
| t _{OEQ} | Output Enable to Output Valid | — | 3.2 | — | 3.4 | ns |
| t _{OEQX} ⁽²⁾ | Output Enable to Output Invalid | 2.5 | — | 2.5 | — | ns |
| t _{OELZ} ^(2,3) | Output Enable to Output Low-Z | 0 | — | 0 | — | ns |
| t _{OEHZ} ^(2,3) | Output Disable to Output High-Z | — | 3.5 | — | 3.5 | ns |
| t _{AS} | Address Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{SS} | Address Status Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{WS} | Read/Write Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{CES} | Chip Enable Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{AVS} | Address Advance Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{DS} | Data Setup Time | 1.5 | — | 1.5 | — | ns |
| t _{AH} | Address Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{WH} | Write Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{SH} | Address Status Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{CEH} | Chip Enable Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{AVH} | Address Advance Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{DH} | Data Hold Time | 0.5 | — | 0.5 | — | ns |
| t _{PDS} | ZZ High to Power Down | — | 2 | — | 2 | cyc |
| t _{PUS} | ZZ Low to Power Down | — | 2 | — | 2 | cyc |

Notes:

1. Configuration signal MODE is static and must not change during normal operation.
2. Guaranteed but not 100% tested. This parameter is periodically sampled.
3. Tested with load in Figure 2.

WRITE CYCLE TIMING



SNOOZE MODE ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Conditions | Min. | Max. | Unit |
|--------|------------------------------------|------------|------|------|-------|
| ISB2 | Current during SNOOZE MODE | ZZ ≥ Vih | — | 60 | mA |
| tPDS | ZZ active to input ignored | | — | 2 | cycle |
| tPUS | ZZ inactive to input sampled | | 2 | — | cycle |
| tZZI | ZZ active to SNOOZE current | | — | 2 | cycle |
| tRZZI | ZZ inactive to exit SNOOZE current | | 0 | — | ns |

SNOOZE MODE TIMING





ORDERING INFORMATION (V_{DD} = 3.3V/V_{DDQ} = 2.5V/3.3V)

Commercial Range: 0°C to +70°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|---------------------|---------------------|
| 128Kx32 | 6.5 | IS61LF12832A-6.5TQ | 100 TQFP |
| | | IS61LF12832A-6.5B2 | 119 PBGA |
| | | IS61LF12832A-6.5B3 | 165 PBGA |
| 128Kx32 | 7.5 | IS61LF12832A-7.5TQ | 100 TQFP |
| | | IS61LF12832A-7.5B2 | 119 PBGA |
| | | IS61LF12832A-7.5B3 | 165 PBGA |
| 128Kx36 | 6.5 | IS61LF12836A-6.5TQ | 100 TQFP |
| | | IS61LF12836A-6.5B2 | 119 PBGA |
| | | IS61LF12836A-6.5B3 | 165 PBGA |
| 128Kx36 | 7.5 | IS61LF12836A-7.5TQ | 100 TQFP |
| | | IS61LF12836A-7.5B2 | 119 PBGA |
| | | IS61LF12836A-7.5B3 | 165 PBGA |
| 256Kx18 | 6.5 | IS61LF25618A-6.5TQ | 100 TQFP |
| | | IS61LF25618A-6.5TQL | 100 TQFP, Lead-free |
| | | IS61LF25618A-6.5B2 | 119 PBGA |
| | | IS61LF25618A-6.5B3 | 165 PBGA |
| 256Kx18 | 7.5 | IS61LF25618A-7.5TQ | 100 TQFP |
| | | IS61LF25618A-7.5B2 | 119 PBGA |
| | | IS61LF25618A-7.5B3 | 165 PBGA |



ORDERING INFORMATION ($V_{DD} = 3.3V/V_{DDQ} = 2.5V/3.3V$)

Industrial Range: -40°C to +85°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|----------------------|---------------------|
| 128Kx32 | 6.5 | IS61LF12832A-6.5TQI | 100 TQFP |
| | | IS61LF12832A-6.5B2I | 119 PBGA |
| | | IS61LF12832A-6.5B3I | 165 PBGA |
| 128Kx32 | 7.5 | IS61LF12832A-7.5TQI | 100 TQFP |
| | | IS61LF12832A-7.5TQLI | 100 TQFP, Lead-free |
| | | IS61LF12832A-7.5B2I | 119 PBGA |
| | | IS61LF12832A-7.5B3I | 165 PBGA |
| 128Kx36 | 6.5 | IS61LF12836A-6.5TQI | 100 TQFP |
| | | IS61LF12836A-6.5TQLI | 100 TQFP, Lead-free |
| | | IS61LF12836A-6.5B2I | 119 PBGA |
| | | IS61LF12836A-6.5B3I | 165 PBGA |
| 128Kx36 | 7.5 | IS61LF12836A-7.5TQI | 100 TQFP |
| | | IS61LF12836A-7.5TQLI | 100 TQFP, Lead-free |
| | | IS61LF12836A-7.5B2I | 119 PBGA |
| | | IS61LF12836A-7.5B3I | 165 PBGA |
| 256Kx18 | 6.5 | IS61LF25618A-6.5TQI | 100 TQFP |
| | | IS61LF25618A-6.5B2I | 119 PBGA |
| | | IS61LF25618A-6.5B3I | 165 PBGA |
| 256Kx18 | 7.5 | IS61LF25618A-7.5TQI | 100 TQFP |
| | | IS61LF25618A-7.5TQLI | 100 TQFP, Lead-free |
| | | IS61LF25618A-7.5B2I | 119 PBGA |
| | | IS61LF25618A-7.5B3I | 165 PBGA |

Automotive Range: -40°C to +125°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|-----------------------|---------------------|
| 128Kx32 | 7.5 | IS64LF12832A-7.5TQA3 | 100 TQFP |
| | | IS64LF12832A-7.5TQLA3 | 100 TQFP, Lead-free |
| 128Kx36 | 7.5 | IS64LF12836A-7.5TQA3 | 100 TQFP |
| | | IS64LF12836A-7.5B3LA3 | 165 PBGA, Lead-free |
| 256Kx18 | 7.5 | IS64LF25618A-7.5TQA3 | 100 TQFP |



ORDERING INFORMATION (V_{DD} = 2.5V /V_{DDQ} = 2.5V)

Commercial Range: 0°C to +70°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|--------------------|----------|
| 128Kx36 | 6.5 | IS61VF12836A-6.5TQ | 100 TQFP |
| | | IS61VF12836A-6.5B2 | 119 PBGA |
| | | IS61VF12836A-6.5B3 | 165 PBGA |
| 128Kx36 | 7.5 | IS61VF12836A-7.5TQ | 100 TQFP |
| | | IS61VF12836A-7.5B2 | 119 PBGA |
| | | IS61VF12836A-7.5B3 | 165 PBGA |
| 256Kx18 | 6.5 | IS61VF25618A-6.5TQ | 100 TQFP |
| | | IS61VF25618A-6.5B2 | 119 PBGA |
| | | IS61VF25618A-6.5B3 | 165 PBGA |
| 256Kx18 | 7.5 | IS61VF25618A-7.5TQ | 100 TQFP |
| | | IS61VF25618A-7.5B2 | 119 PBGA |
| | | IS61VF25618A-7.5B3 | 165 PBGA |

Industrial Range: -40°C to +85°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|---------------------|----------|
| 128Kx36 | 6.5 | IS61VF12836A-6.5TQI | 100 TQFP |
| | | IS61VF12836A-6.5B2I | 119 PBGA |
| | | IS61VF12836A-6.5B3I | 165 PBGA |
| 128Kx36 | 7.5 | IS61VF12836A-7.5TQI | 100 TQFP |
| | | IS61VF12836A-7.5B2I | 119 PBGA |
| | | IS61VF12836A-7.5B3I | 165 PBGA |
| 256Kx18 | 6.5 | IS61VF25618A-6.5TQI | 100 TQFP |
| | | IS61VF25618A-6.5B2I | 119 PBGA |
| | | IS61VF25618A-6.5B3I | 165 PBGA |
| 256Kx18 | 7.5 | IS61VF25618A-7.5TQI | 100 TQFP |
| | | IS61VF25618A-7.5B2I | 119 PBGA |
| | | IS61VF25618A-7.5B3I | 165 PBGA |

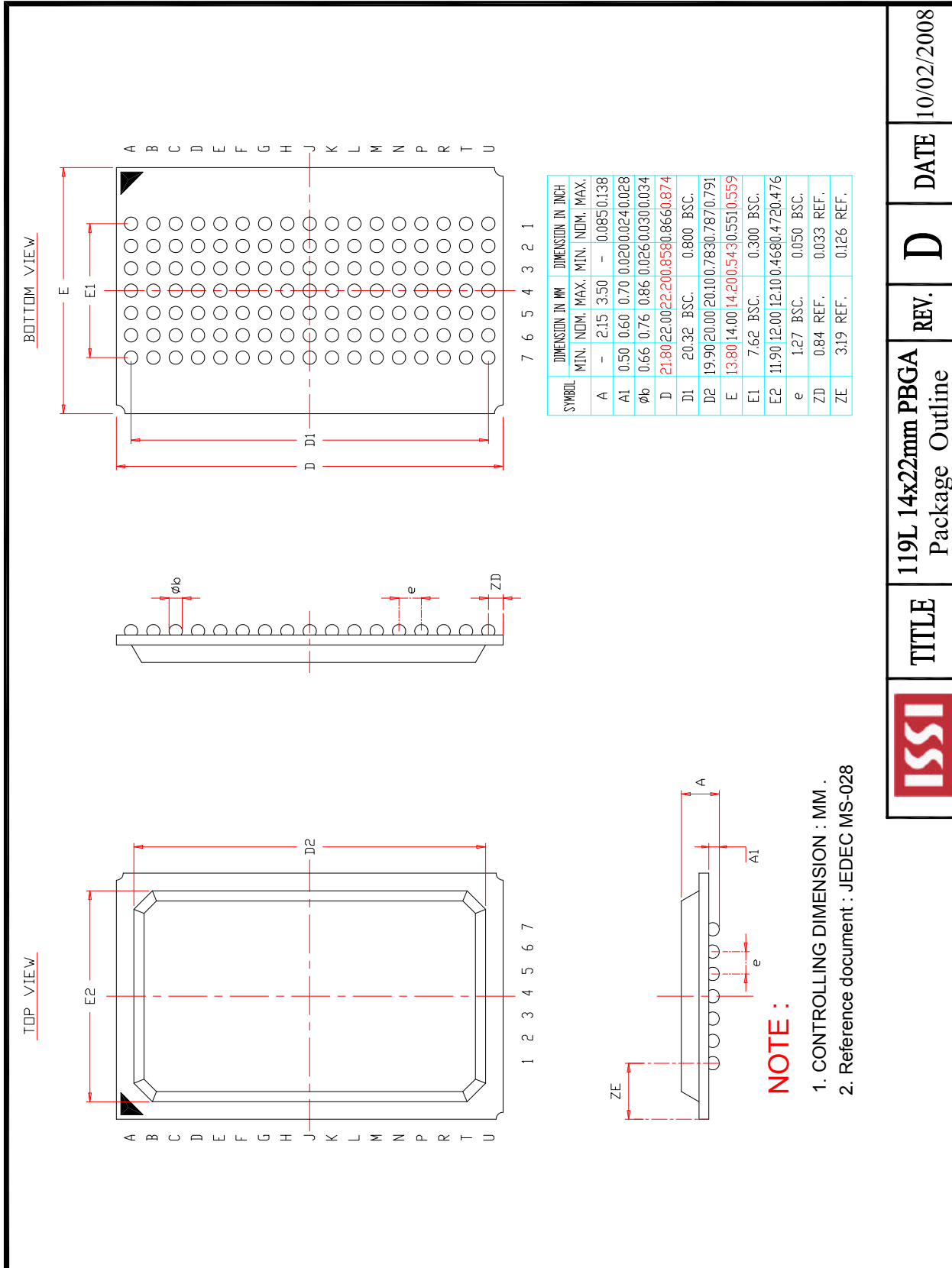
Automotive Range: -40°C to +125°C

| Configuration | Access Time | Order Part Number | Package |
|---------------|-------------|-----------------------|---------------------|
| 128Kx32 | 7.5 | IS64VF12832A-7.5TQLA3 | 100 TQFP, Lead-free |
| 128Kx36 | 7.5 | IS64VF12836A-7.5TQA3 | 100 TQFP |
| 256Kx18 | 7.5 | IS64VF25618A-7.5TQA3 | 100 TQFP |



| | | | |
|--|---|------|------------|
| | TITLE | REV. | DATE |
| | 100L14x20x1.4mm LQFP (Footprint : 2.0 mm) Package Outline | F | 09/01/2009 |

280-600-011 REV. A



| | | | | | | |
|--|-------|--------------------------------------|------|---|------|------------|
| | TITLE | 119L 14x22mm PBGA Package Outline | REV. | D | DATE | 10/02/2008 |
|--|-------|--------------------------------------|------|---|------|------------|



| | | | | | | |
|--|--------------|--|-------------|----------|-------------|------------|
| | TITLE | 165L 13x15mm TF-BGA Package Outline | REV. | B | DATE | 08/28/2008 |
|--|--------------|--|-------------|----------|-------------|------------|

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9